

PCB Manufacturing Notes

General Info

Board dimensions – 40mm x 70mm
Number of layers – 2
Smallest hole – 0.3mm
Number of holes – Approx 180
Minimum Track & Gap – 0.15mm
RoHS/Lead Free – Yes
Material – FR4 or equivalent

Stackup

Stackup is to be as follows:

Layer	Copper Weight (Pre-Plating)
	0.5oz
	0.5oz

Finished board thickness to be 1.6mm ± 0.1mm

Impedance Control

Not required.

Copper Thieving/Balancing

The supplier may not add copper thieving/balancing.

Finish

A.) Conductive finish

Plating to be immersion gold.

B.) Soldermask

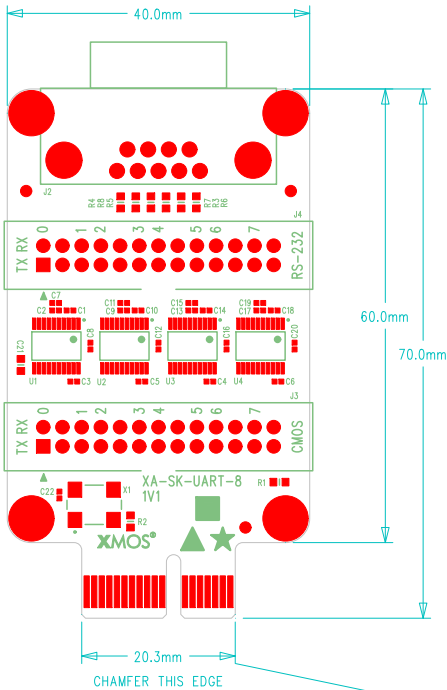
Liquid photo imageable soldermask (green). Pads have not been oversized.
Supplier should oversize soldermask on pads to suit process.

C.) Silkscreen

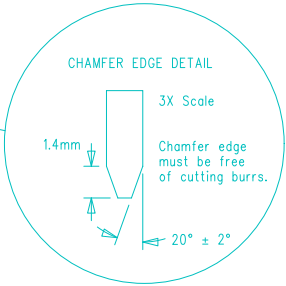
Colour white. Supplier should remove any silkscreen which overhangs pads.

Drill Data

Drill data is in Excellon format, metric (000.000), no zero suppression, absolute coordinates.
Hole size is finished size.



XMOS LTD = XPCB-056 = 1V1 = 2 AUGUST 2012
LAYER - FABRICATION INSTRUCTIONS



XMOS

Project Name
XPCB-056 (XA-SK-UART8)

Sheet	Date	Revision
A4	2 AUGUST 2012	1V1

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PCB Manufacturing Notes

General Info

Board dimensions – 40mm x 70mm
Number of layers – 2
Smallest hole – 0.3mm
Number of holes – Approx 180
Minimum Track & Gap – 0.15mm
RoHS/Lead Free – Yes
Material – FR4 or equivalent

Stackup

Stackup is to be as follows:

Layer	Copper Weight (Pre-Plating)
Layer 01 (Top)	0.5oz
	0.5oz

Finished board thickness to be 1.6mm ± 0.1mm

Impedance Control

Not required.

Copper Thieving/Balancing

The supplier may not add copper thieving/balancing.

Finish

A.) Conductive finish

Plating to be immersion gold.

B.) Soldermask

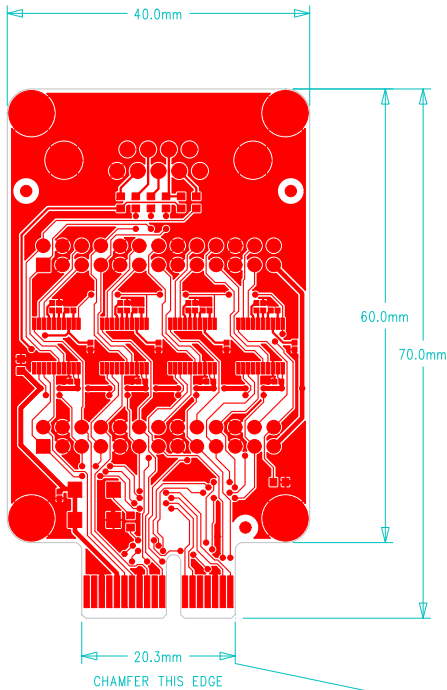
Liquid photo imageable soldermask (green). Pads have not been oversized.
Supplier should oversize soldermask on pads to suit process.

C.) Silkscreen

Colour white. Supplier should remove any silkscreen which overhangs pads.

Drill Data

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Hole size is finished size.



XMOS LTD = XPCB-056 = 1V1 = 2 AUGUST 2012
LAYER - P6BRCOPPER LAYER 01 (TOP)

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Project Name XPCB-056 (XA-SK-UART8)		
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PCB Manufacturing Notes

General Info

Board dimensions – 40mm x 70mm
Number of layers – 2
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Number of holes – Approx 180
Minimum Track & Gap – 0.15mm
RoHS/Lead Free – Yes
Material – FR4 or equivalent

Stackup

Stackup is to be as follows:

Layer	Copper Weight (Pre-Plating)
	0.5oz
Layer 02 (Bottom)	0.5oz

Finished board thickness to be 1.6mm ± 0.1mm

Impedance Control

Not required.

Copper Thieving/Balancing

The supplier may not add copper thieving/balancing.

Finish

A.) Conductive finish

Plating to be immersion gold.

B.) Soldermask

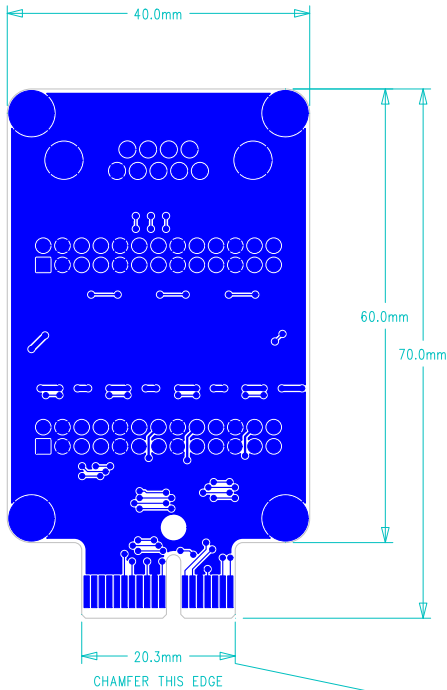
Liquid photo imageable soldermask (green). Pads have not been oversized.
Supplier should oversize soldermask on pads to suit process.

C.) Silkscreen

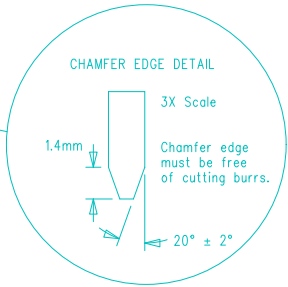
Colour white. Supplier should remove any silkscreen which overhangs pads.

Drill Data

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XMOS LTD = XPCB-056 = 1V1 = 2 AUGUST 2012
LAYER - P6BRCOPPER LAYER 02 (BOTTOM)



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PCB Manufacturing Notes

General Info

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Smallest hole – 0.3mm
Number of holes – Approx 180
Minimum Track & Gap – 0.15mm
RoHS/Lead Free – Yes
Material – FR4 or equivalent

Stackup

Stackup is to be as follows:

Layer	Copper Weight (Pre-Plating)
	0.5oz
	0.5oz

Finished board thickness to be 1.6mm ± 0.1mm

Impedance Control

Not required.

Copper Thieving/Balancing

The supplier may not add copper thieving/balancing.

Finish

A.) Conductive finish

Plating to be immersion gold.

B.) Soldermask

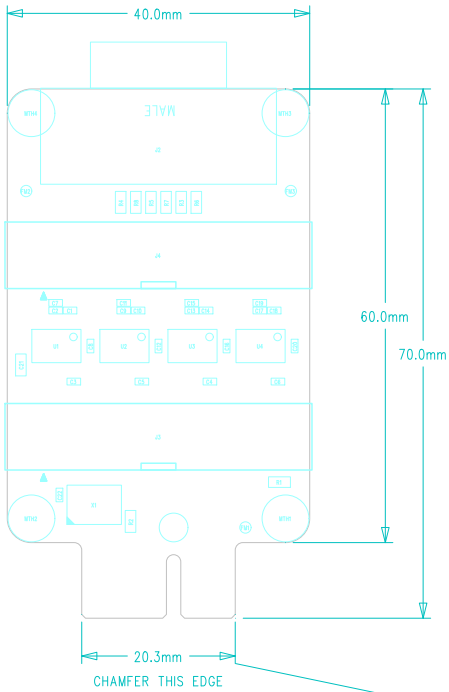
Liquid photo imageable soldermask (green). Pads have not been oversized.
Supplier should oversize soldermask on pads to suit process.

C.) Silkscreen

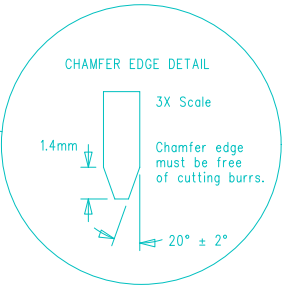
Colour white. Supplier should remove any silkscreen which overhangs pads.

Drill Data

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Hole size is finished size.



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LAYER - FABRICATION INSTRUCTIONS



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PCB Manufacturing Notes

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RoHS/Lead Free – Yes
Material – FR4 or equivalent

Stackup

Stackup is to be as follows:

Layer	Copper Weight (Pre-Plating)
Layer 01 (Top)	0.5oz
Layer 02 (Bottom)	0.5oz

Finished board thickness to be 1.6mm ± 0.1mm

Impedance Control

Not required.

Copper Thieving/Balancing

The supplier may not add copper thieving/balancing.

Finish

A.) Conductive finish

Plating to be immersion gold.

B.) Soldermask

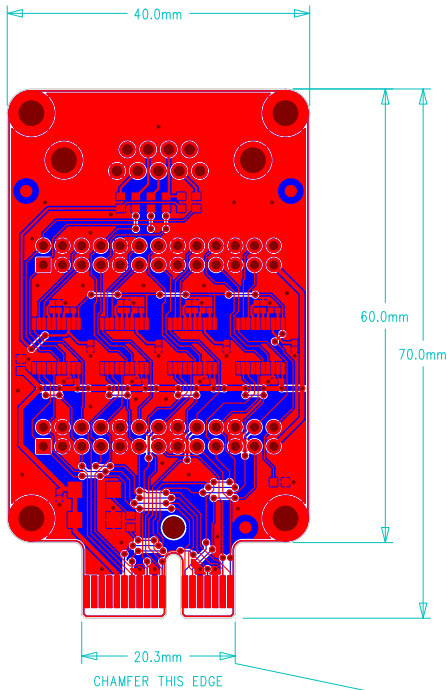
Liquid photo imageable soldermask (green). Pads have not been oversized.
Supplier should oversize soldermask on pads to suit process.

C.) Silkscreen

Colour white. Supplier should remove any silkscreen which overhangs pads.

Drill Data

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XMOS LTD = XPCB-056 = 1V1 = 2 AUGUST 2012
LAYER - P6B COPPER LAYER 02 (BOTTOM)

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